

ABSTRACT

A film carrier tape for mounting an electronic part of the present invention is a film carrier tape comprising a long insulating film and a large number of wiring patterns formed on a surface of the insulating film, said wiring patterns being made of a conductive metal, wherein the wiring patterns are each independently covered with a solder resist layer except a connecting terminal portion, and the solder resist layer formed on each surface of the wiring patterns is split and/or divided into plural sections. According to the present invention, warpage distortion that occurs on each of a plural film carriers arranged, such as CSP, COF and BGA, provided in a film carrier tape for mounting an electronic part in the width direction of the tape can be reduced.